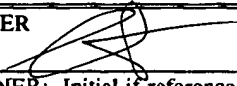


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| Form PTO-1449 (Modified) | U.S. Department of Commerce Patent and Trademark Office | Atty. Docket No. | Serial No. |
| | | 29926/39504 | To be Assigned |
| | | Applicant | |
| | | 10/669 996 | |
| INFORMATION DISCLOSURE STATEMENT | | Ju-Il Lee | |
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| U.S. PATENT DOCUMENTS | | | | | | | |
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| | | | | | | | Yes | No |
| | | | | | | | | |

| OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.) | | |
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